

4.4 TMS70C02, TMS70C42, and TMS70C82 Specifications (Wide Voltage)

Table 4-20. Absolute Maximum Ratings Over Operating Free-Air Temperature Range for the TMS70C02, TMS70C42, and TMS70C82 (Unless Otherwise Noted)

Supply voltage range, V_{CC}	- 0.3V to 7 V
Input voltage range	- 0.3V to $V_{CC}+0.3$ V
Output voltage range	- 0.3V to $V_{CC}+0.3$ V
Maximum I/O buffer current (per pin)	±10 mA
Storage temperature range	- 55°C to 150°C
I_{CC}, I_{SS} (maximum into pin 25 or 40)	±60 mA
Continuous power dissipation	0.5 W

† Unless otherwise noted, all voltages are with respect to V_{SS} .

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the "Recommended Operating Conditions" section of this specification is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

Table 4-21. Recommended Operating Conditions for the TMS70C02, TMS70C42, and TMS70C82

V_{CC}	Supply voltage		Min	Nom	Max	Unit
V_{IH}	High-level input voltage	MC and XTAL2 pins, $V_{CC} = 2.5$ to 6 V	0.8 V_{CC}			V
		All other input pins, $V_{CC} = 3$ to 6 V	0.70 V_{CC}			V
		All other input pins, $V_{CC} = 2.5$ to 3 V	0.75 V_{CC}			V
V_{IL}	Low-level input voltage	MC and XTAL2 pins, $V_{CC} = 2.5$ to 6 V		0.2 V_{CC}		V
		All other input pins, $V_{CC} = 2.5$ to 6 V		0.3 V_{CC}		V
TA	Operating free-air temperature	Commercial (TMS70C42NL)	0	70		°C
		Industrial (TMS70C42NA)	- 40	85		°C

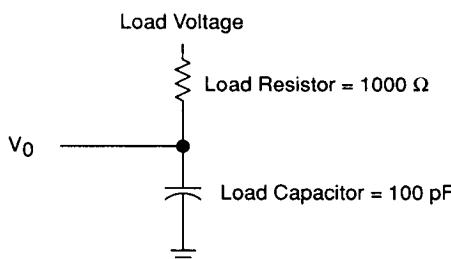
Table 4–22. Electrical Characteristics Over Full Range of Operating Conditions for the TMS70C02, TMS70C42, and TMS70C82

Parameter		Test Conditions	Min	Typ	Max	Unit
I _I	Input current	MC pin, V _{IN} = V _{SS} or V _{CC} All others, V _{IN} = V _{SS} to V _{CC}		±0.1	±5	µA
C _I	Input capacitance			5		pF
V _{OH}	High-level output voltage ‡	V _{CC} = 2.5 V, I _{OH} = – 50 mA	2.25	2.4		V
		V _{CC} = 4.0 V, I _{OH} = – 0.4 mA	3.2	3.6		V
		V _{CC} = 5.0 V, I _{OH} = – 0.7 mA	3.9	4.5		V
		V _{CC} = 6.0 V, I _{OH} = – 1.0 mA	4.6	5.4		V
V _{OL}	Low-level output voltage ‡	V _{CC} = 2.5 V, I _{OL} = 0.4 mA		0.2	0.35	V
		V _{CC} = 4.0 V, I _{OL} = 1.6 mA		0.4	0.8	V
		V _{CC} = 5.0 V, I _{OL} = 2.5 mA		0.6	1.1	V
		V _{CC} = 6.0 V, I _{OL} = 3.4 mA		0.8	1.4	V
I _{OH}	Output source current	V _{CC} = 2.5 V, V _{OH} = 2.25 V	–50	–200		µA
		V _{CC} = 4.0 V, V _{OH} = 3.2 V	–0.4	–1.4		mA
		V _{CC} = 5.0 V, V _{OH} = 3.9 V	–0.7	–2.2		mA
		V _{CC} = 6.0 V, V _{OH} = 4.6 V	–1.0	–3.3		mA
I _{OL}	Output sink current	V _{CC} = 2.5 V, V _{OL} = 0.35 V	0.4	0.9		mA
		V _{CC} = 4.0 V, V _{OL} = 0.8 V	1.6	3.5		mA
		V _{CC} = 5.0 V, V _{OL} = 1.1 V	2.5	5.5		mA
		V _{CC} = 6.0 V, V _{OL} = 1.4 V	3.4	8.0		mA

† V_{CC} = 5 V, T_A = 25°C

‡ Output levels ensure 400 mV of noise margin over specified input levels.

Figure 4–15. Output Loading Circuit for Test for the TMS70C02, TMS70C42, and TMS70C82



Note: Rise and fall times are measured between the maximum low level and the minimum high level using the 10% and 90% points.

Table 4-23. Supply Current Requirements for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Test Conditions	Min	Typ	Max	Unit
I_{CC} Operating mode	$f_{osc} = 7.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	17	24.5	mA	
	$f_{osc} = 3.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	7.2	10.5	mA	
	$f_{osc} = 0.5 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	1.2	1.8	mA	
	$f_{osc} = Z \text{ MHz}, V_{CC} = 5.0 \text{ V}$	2.4	3.5	mA/MHz	
	$f_{osc} = 0.5 \text{ MHz}, V_{CC} = 2.5 \text{ V}$	0.4	1.2	mA	
I_{CC} Wake-up mode 1 (one timer and UART active)	$f_{osc} = 7.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	2400	5600	μA	
	$f_{osc} = 3.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	1200	3300	μA	
	$f_{osc} = 0.5 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	250	800	μA	
I_{CC} Wake-up mode 2 (one timer active and UART inactive)	$f_{osc} = 7.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	960	3400	μA	
	$f_{osc} = 3.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	480	2000	μA	
	$f_{osc} = 0.5 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	140	550	μA	
I_{CC} Wake-up mode 3 (UART active only)	$f_{osc} = 7.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	1500	2400	μA	
	$f_{osc} = 3.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	800	1500	μA	
	$f_{osc} = 0.5 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	180	600	μA	
I_{CC} Halt OSC-ON	$f_{osc} = 7.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	560	1280	μA	
	$f_{osc} = 3.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	240	560	μA	
	$f_{osc} = 1.0 \text{ MHz}, V_{CC} = 5.0 \text{ V}$	80	200	μA	
	$f_{osc} = Z \text{ MHz}$	(See Note 2)		μA	
I_{CC} Halt OSC-OFF		5	10	μA	

Notes: 1) All inputs = V_{CC} or V_{SS} (except XTAL2). All I/O and output pins are open.

2) Maximum current = $180(Z) + 20 \mu\text{A}$.

Table 4-24. Recommended Crystal/Clockin Operating Conditions Over Full Operating Range for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Test Conditions	Min	Typ†	Max	Unit
f_{osc} Crystal frequency	$V_{CC} = 2.5\text{ V}$	0.5	0.8	0.8	MHz
	$V_{CC} = 4.0\text{ V}$	0.5	5.0	5.0	MHz
	$V_{CC} = 5.0\text{ V}$	0.5	7.0	7.0	MHz
	$V_{CC} = 6.0\text{ V}$	0.5	7.5	7.5	MHz
CLKIN duty cycle		47	53	53	%
$t_c(P)$ CLKIN cycle time	$V_{CC} = 2.5\text{ V}$	333	2000	ns	
	$V_{CC} = 4.0\text{ V}$	167	2000	ns	
	$V_{CC} = 5.0\text{ V}$	143	2000	ns	
	$V_{CC} = 6.0\text{ V}$	133	2000	ns	
$t_c(C)$ Internal state cycle time	$V_{CC} = 2.5\text{ V}$	666	4000	ns	
	$V_{CC} = 4.0\text{ V}$	333	4000	ns	
	$V_{CC} = 5.0\text{ V}$	286	4000	ns	
	$V_{CC} = 6.0\text{ V}$	267	4000	ns	
$t_w(\text{PH})$	CLKIN pulse duration high	50			ns
$t_w(\text{PL})$	CLKIN pulse duration low	50			ns
t_r	CLKIN rise time		30	30	ns
t_f	CLKIN fall time		30	30	ns
$t_d(\text{PL-CH})$	CLKIN fall to CLKOUT rise	110	250	250	ns

† $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

Figure 4-16. Clock Timing for the TMS70C02, TMS70C42, and TMS70C82

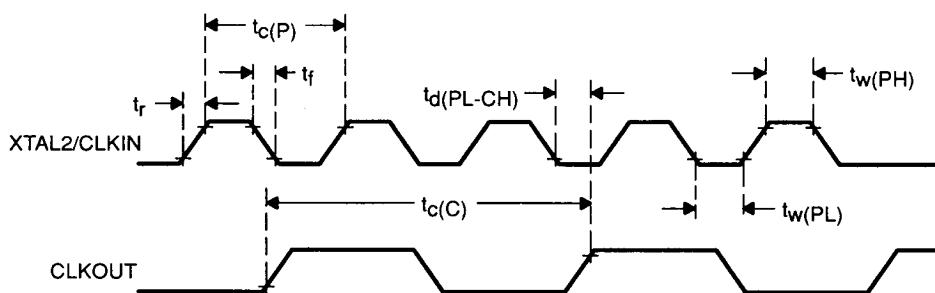


Figure 4-17. Operating Frequency Range for the TMS70C02, TMS70C42, and TMS70C82

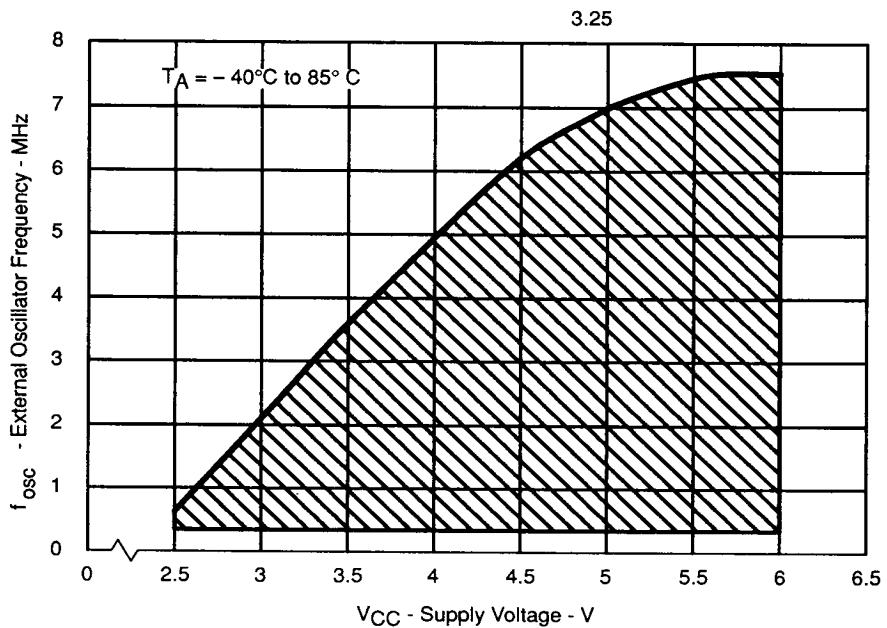


Figure 4-18. Typical Operating Current vs. Supply Voltage for the TMS70C02, TMS70C42, and TMS70C82

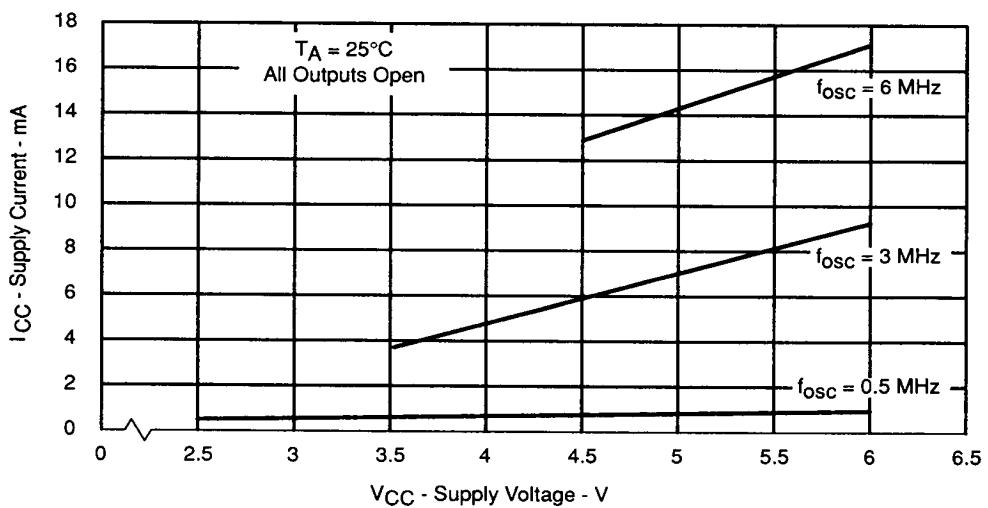


Figure 4-19. Typical Operating I_{CC} vs. Oscillator Frequency for the TMS70C02, TMS70C42, and TMS70C82

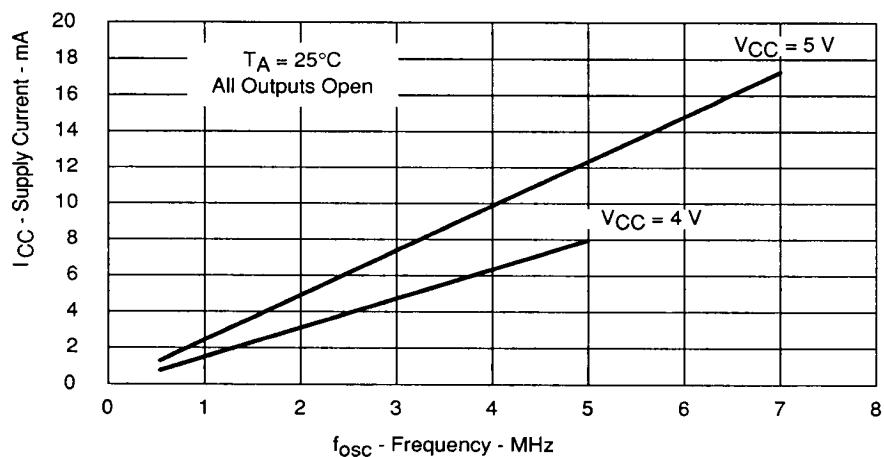


Figure 4-20. Typical Operating Current vs. Supply Voltage for the TMS70C02, TMS70C42, and TMS70C82

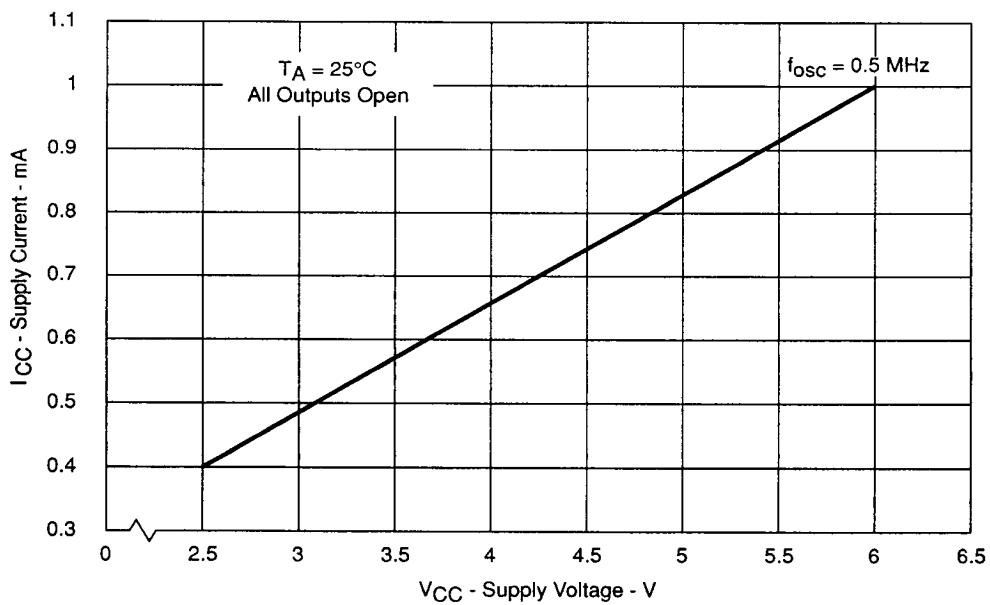


Figure 4-21. Typical Output Source Characteristics for the TMS70C02, TMS70C42, and TMS70C82

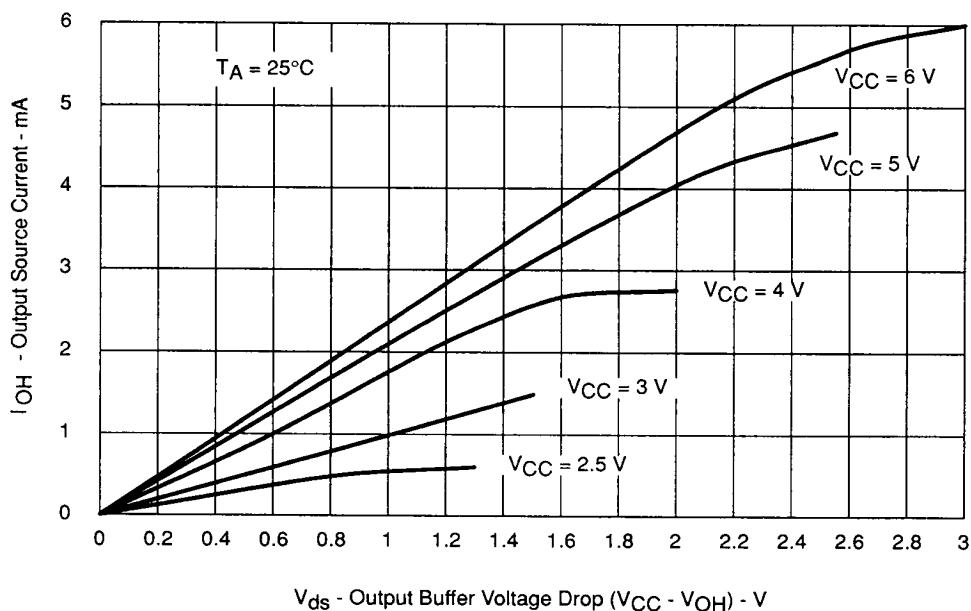
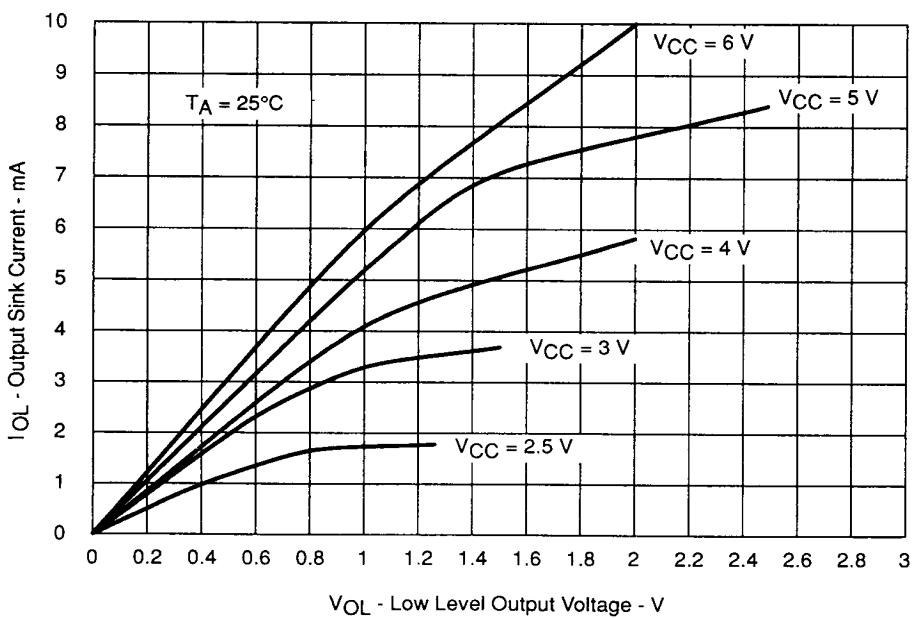


Figure 4-22. Typical Output Sink Characteristics for the TMS70C02, TMS70C42, and TMS70C82



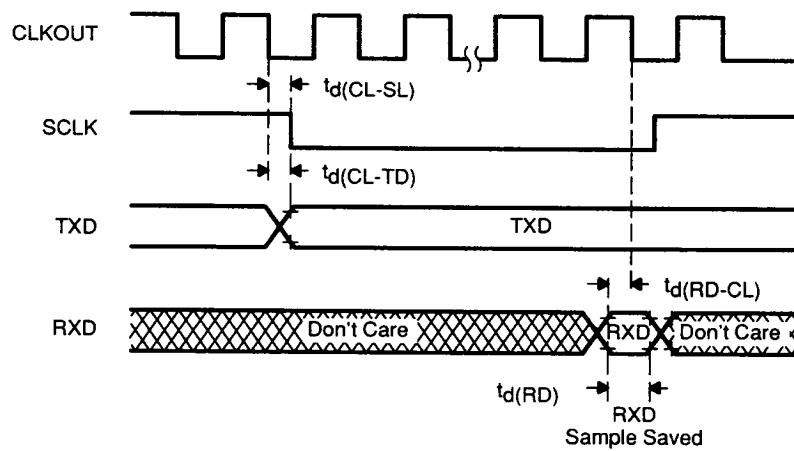
4.4.1 Serial Port Timing

4.4.1.1 Internal Serial Clock

Table 4-25. Timing Parameters for Internal Serial Clock for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Typ	Unit
$t_d(CL-SL)$ CLKOUT low to SCLK low	$1/4 t_c(C)$	ns
$t_d(CL-TD)$ CLKOUT low to new TXD data	$1/4 t_c(C)$	ns
$t_d(RD-CL)$ RXD data valid before CLKOUT low	$1/4 t_c(C)$	ns
$t_d(RD)$ RXD data valid time	$1/2 t_c(C)$	ns

Figure 4-23. Timing Diagram for Internal Serial Clock for the TMS70C02, TMS70C42, and TMS70C82



Notes:

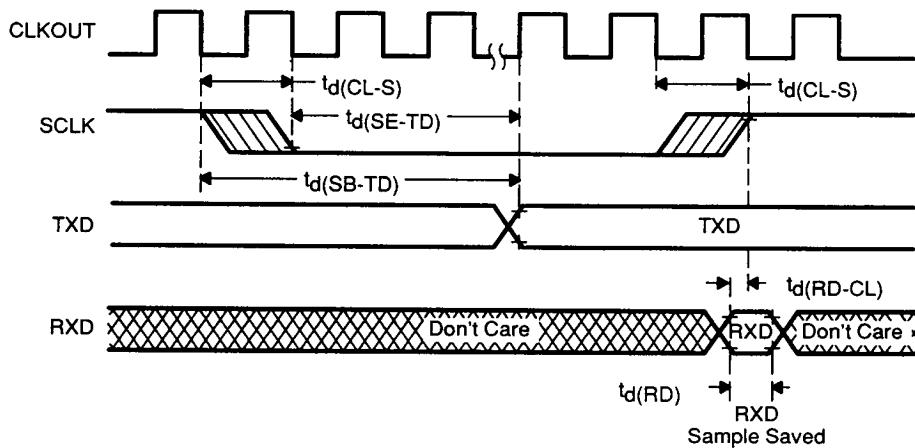
- 1) The CLKOUT signal is not available in single-chip mode.
- 2) $CLKOUT = t_c(C)$.

4.4.1.2 External Serial Clock

Table 4-26. Timing Parameters for External Serial Clock for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Typ	Unit
$t_d(RD-CL)$ RXD data valid before CLKOUT low	$1/4 t_c(C)$	ns
$t_d(RD)$ RXD data valid time	$1/2 t_c(C)$	ns
$t_d(SB-TD)$ Start of SCLK sample to new TXD data	$3 1/4 t_c(C)$	ns
$t_d(SE-TD)$ End of SCLK sample to new TXD data	$2 1/4 t_c(C)$	ns
$t_d(CL-S)$ Clockout low to SCLK transition	$t_c(C)$	ns

Figure 4-24. Timing Diagram for External Serial Clock for the TMS70C02, TMS70C42, and TMS70C82



- Notes:**
- 1) The CLKOUT signal is not available in single-chip mode.
 - 2) $CLKOUT = t_c(C)$.
 - 3) SCLK sampled; if SCLK = 1 then 0, fall transition found.
 - 4) SCLK sampled; if SCLK = 0 then 1, rise transition found.

4.5 TMS70C02, TMS70C42, and TMS70C82 Specifications (5V ±10%)

Table 4-27. Absolute Maximum Ratings Over Operating Free-Air Temperature Range for the TMS70C02, TMS70C42, and TMS70C82 (Unless Otherwise Noted)

Supply voltage range, V_{CC}	-0.3 V to 7 V
Input voltage range	-0.3 V to $V_{CC}+0.3$ V
Output voltage range	-0.3 V to $V_{CC}+0.3$ V
Maximum I/O buffer current (per pin)	±10 mA
Storage temperature range	-55°C to 150°C
I_{CC}, I_{SS} (maximum into pin 25 or 40)	±60 mA
Continuous power dissipation	0.5 W

† Unless otherwise noted, all voltages are with respect to V_{SS} .

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the "Recommended Operating Conditions" section of this specification is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

Table 4-28. Recommended Operating Conditions for the TMS70C02, TMS70C42, and TMS70C82

			Min	Nom	Max	Unit
V_{CC}	Supply voltage		4.5		5.5	V
V_{IH}	High-level input voltage	MC and XTAL2 pins	0.8 V_{CC}			V
		All other input pins	0.7 V_{CC}			V
V_{IL}	Low-level input voltage	MC and XTAL2 pins		0.3 V_{CC}		V
		All other input pins		0.2 V_{CC}		V
T_A	Operating temperature	Commercial (TMS70C42NL)	0		70	°C
		Industrial (TMS70C42NA)	-40		85	°C

Table 4-29. Electrical Characteristics Over Full Range of Operating Conditions for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Test Conditions	Min	Typt	Max	Unit
I _I Input leakage current	MC pin, V _{IN} = V _{SS} or V _{CC} All others, V _{IN} = V _{SS} to V _{CC}		±0.1	±5	µA
C _I Input capacitance			5		pF
V _{OH} High-level output voltage	V _{CC} = 5.0 V, I _{OH} = -0.3 mA	V _{CC} -0.05	4.7		V
V _{OL} Low-level output voltage	V _{CC} = 5.0 V, I _{OL} = 1.4 mA		0.2	0.4	V
I _{OH} High-level output source current	V _{OH} = V _{CC} - 0.5 V		-0.3	-1.2	mA
	V _{OH} = 2.5 V min		-1.0	-3.0	mA
I _{OL} Output sink current	V _{OL} = 0.4 V	1.4	2.0		mA

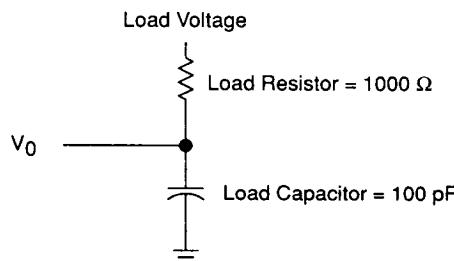
† Rise and fall times are measured between the maximum low level and the minimum high level using the 10% and 90% points.

Table 4-30. AC Characteristics for Input/Output Ports† for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Test Conditions	Min	Typt	Max	Unit
t _r (IO) I/O port output rise time	C _{load} = 15 pF, V _{CC} = 5 V		35	60	ns
t _f (IO) I/O port output fall time	C _{load} = 15 pF, V _{CC} = 5 V		20	50	ns

† Rise and fall times are measured between the maximum low level and the minimum high level using the 10% and 90% points.

Figure 4-25. Output Loading Circuit for Test for the TMS70C02, TMS70C42, and TMS70C82



Note: Rise and fall times are measured between the maximum low level and the minimum high level using the 10% and 90% points.

Figure 4-26. Measurement Points for Switching Characteristics for the TMS70C02, TMS70C42, and TMS70C82

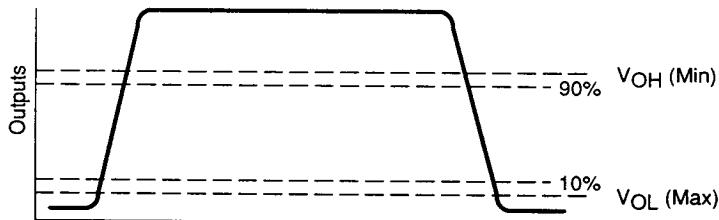


Table 4-31. Supply Current Requirements for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Test Conditions	Min	Typ	Max	Unit
I _{CC} Supply current	f _{osc} = 6.0 MHz	15	24		mA
	f _{osc} = 3.0 MHz	7.2	12		mA
	f _{osc} = 1.0 MHz	2.4	4.0		mA
	f _{osc} = Z MHz	2.4	4.0		mA/MHz
I _{CC} Wake-up mode 1 (one timer and UART active)	f _{osc} = 6.0 MHz	2400	5400		µA
	f _{osc} = 3.0 MHz	1200	2900		µA
	f _{osc} = 1.0 MHz	650	1500		µA
I _{CC} Wake-up mode 2 (one timer active, and UART inactive)	f _{osc} = 6.0 MHz	960	3200		µA
	f _{osc} = 3.0 MHz	480	1800		µA
	f _{osc} = 1.0 MHz	350	1000		µA
I _{CC} Wake-up mode 3 (UART active only)	f _{osc} = 6.0 MHz	1500	2200		µA
	f _{osc} = 3.0 MHz	800	1300		µA
	f _{osc} = 1.0 MHz	400	1100		µA
I _{CC} Halt OSC-ON	f _{osc} = 6.0 MHz	480	1120		µA
	f _{osc} = 3.0 MHz	240	560		µA
	f _{osc} = 1.0 MHz	80	200		µA
	f _{osc} = Z MHz	(See Note 2)			µA
I _{CC} Halt OSC-OFF		5	10		µA

Notes: 1) All inputs = V_{CC} or V_{SS} (except XTAL2). All output pins are open.

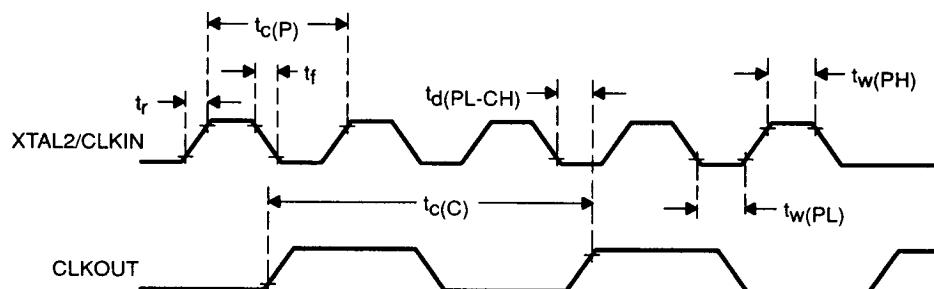
2) Maximum current = 180(Z) + 20 µA.

Table 4-32. Recommended Crystal/Clockin Operating Conditions Over Full Operating Range for the TMS70C02, TMS70C42, and TMS70C82

Parameter		Min	Typ	Max	Unit
f_{osc}	CLKIN frequency	0.5	6.0	6.0	MHz
	CLKIN duty cycle	45	55	55	%
$t_c(P)$	CLKIN cycle time	167	2000	2000	ns
$t_c(C)$	Internal state cycle time	333	4000	4000	ns
$t_w(PH)$	CLKIN pulse duration high	70			ns
$t_w(PL)$	CLKIN pulse duration low	70			ns
t_r	CLKIN rise time			30	ns
t_f	CLKIN fall time			30	ns
$t_d(PL-CH)$	CLKIN fall to CLKOUT rise delay	110	250	250	ns

† $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$

Figure 4-27. Clock Timing for the TMS70C02, TMS70C42, and TMS70C82



Note: Period of internal clock $t_c(C) = 2 \times t_c(P) = 2 / f_{osc}$. Timings are given in $t_c(C)$.

Table 4-33. Memory Interface Timingst for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Min	Type†	Max	Unit
$t_{c(C)}$ CLKOUT cycle time	333		4000	ns
$t_{w(CH)}$ CLKOUT high pulse duration	$0.5t_{c(C)} - 90$	$0.5t_{c(C)}$	$0.5t_{c(C)} + 90$	ns
$t_{w(CL)}$ CLKOUT low pulse duration	$0.5t_{c(C)} - 90$	$0.5t_{c(C)}$	$0.5t_{c(C)} + 90$	ns
$t_d(CH-JL)$ Delay time, CLKOUT rise to ALATCH fall	$0.5t_{c(C)} - 50$	$0.5t_{c(C)}$		ns
$t_w(JH)$ ALATCH high pulse duration	$0.25t_{c(C)} - 50$	$0.25t_{c(C)}$		ns
$t_{su(HA-JL)}$ Setup time, high address valid before ALATCH fall	$0.25t_{c(C)} - 45$	$0.25t_{c(C)}$		ns
$t_{su(LA-JL)}$ Setup time, low address valid before ALATCH fall	$0.25t_{c(C)} - 45$	$0.25t_{c(C)}$		ns
$t_d(JL-LA)$ Delay time, low address valid after ALATCH fall	$0.5t_{c(C)} - 35$	$0.5t_{c(C)}$		ns
$t_{su(RW-JL)}$ Setup time, R/W valid before ALATCH fall	$0.25t_{c(C)} - 40$	$0.25t_{c(C)}$		ns
$t_h(EH-RW)$ Hold time, R/W valid after $\overline{\text{ENABLE}}$ rise	$0.5t_{c(C)} - 60$	$0.5t_{c(C)}$		ns
$t_h(EH-HA)$ Hold time, high address valid after $\overline{\text{ENABLE}}$ rise	$0.5t_{c(C)} - 60$	$0.5t_{c(C)}$		ns
$t_{su(Q-EH)}$ Setup time, data out valid before $\overline{\text{ENABLE}}$ rise	$0.5t_{c(C)} - 70$	$0.5t_{c(C)}$		ns
$t_h(EH-Q)$ Hold time, data out valid after $\overline{\text{ENABLE}}$ rise	$0.5t_{c(C)} - 60$	$0.5t_{c(C)}$		ns
$t_d(LA-EL)$ Delay time, low address high-Z to $\overline{\text{ENABLE}}$ fall	$.25t_{c(C)} - 45$	$0.25t_{c(C)}$		ns
$t_d(EH-A)$ Delay time, $\overline{\text{ENABLE}}$ rise to next address drive	$0.5t_{c(C)} - 60$	$0.5t_{c(C)}$		ns
$t_d(EL-D)$ Delay time, data in after $\overline{\text{ENABLE}}$ fall	$0.75t_{c(C)} - 160$	$0.75t_{c(C)}$		ns
$t_a(A-D)$ Access time, data in from valid address	$1.5t_{c(C)} - 200$	$1.5t_{c(C)} - 100$		ns
$t_d(A-EH)$ Delay time, $\overline{\text{ENABLE}}$ high after address valid	$1.5t_{c(C)} - 50$	$1.5t_{c(C)}$		ns
$t_h(EH-D)$ Hold time, Data input valid after $\overline{\text{ENABLE}}$ rise	0			ns
$t_d(EH-JH)$ Delay time, $\overline{\text{ENABLE}}$ rise to ALATCH rise	$0.5t_{c(C)} - 60$	$0.5t_{c(C)}$		ns
$t_d(CH-EL)$ Delay time, CLKOUT rise to $\overline{\text{ENABLE}}$ fall		30		ns

† $V_{CC} = 5 \text{ V} \pm 10\%$, $t_{c(C)} = 2/\text{freq}$

CLKIN duty cycle = 50%

 $f_{osc} = 0.5 \text{ to } 6.0 \text{ MHz}$

Table 4-34. Memory Interface Timings at 6 MHz^t for the TMS70C02, TMS70C42, and TMS70C82

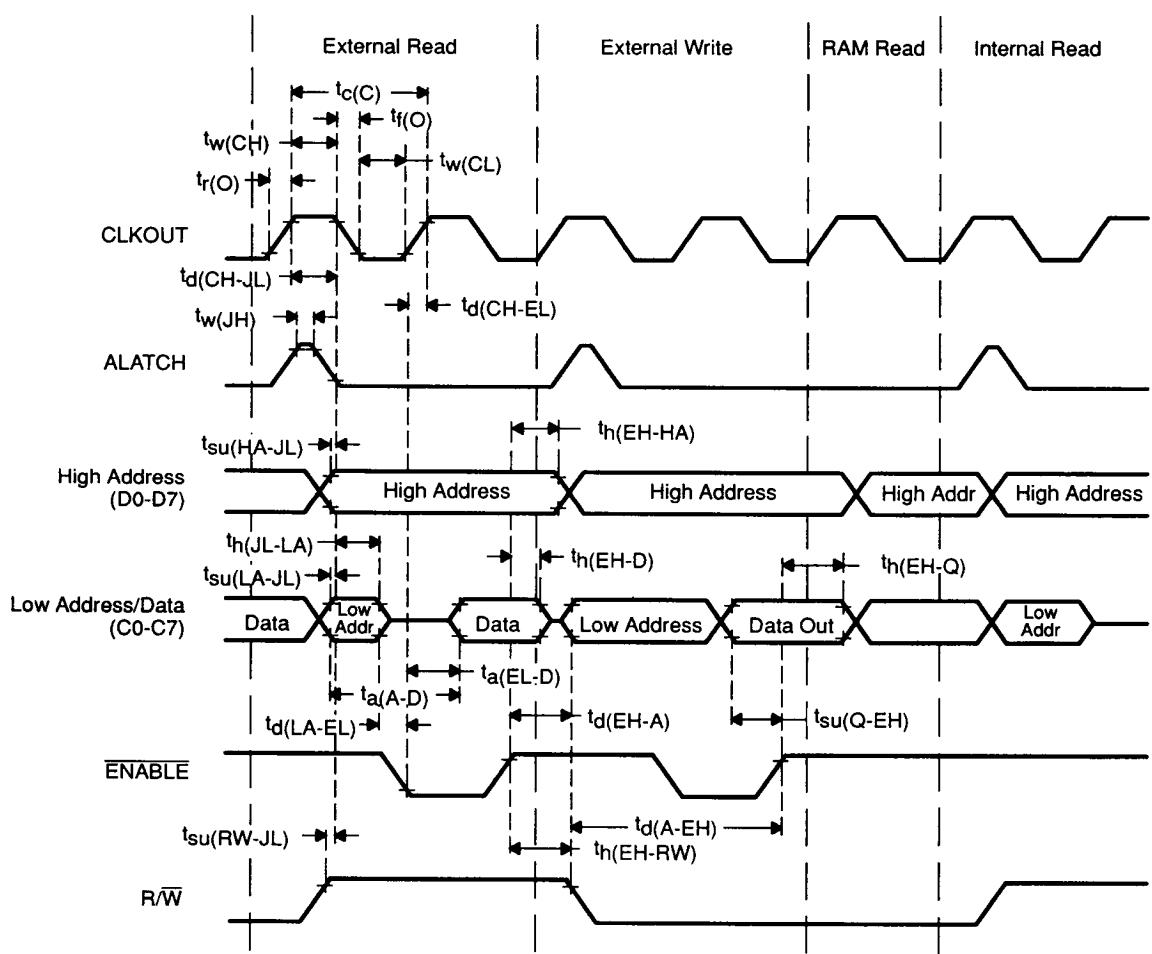
Parameter	Min	Type†	Max	Unit
$t_{c(C)}$ CLKOUT cycle time		333		ns
$t_w(CH)$ CLKOUT high pulse duration	76	166	252	ns
$t_w(CL)$ CLKOUT low pulse duration	76	162	252	ns
$t_d(CH-JL)$ Delay time, CLKOUT rise to ALATCH fall	116	166		ns
$t_w(JH)$ ALATCH active duration	33	83		ns
$t_{su}(AH-JL)$ Setup time, high address valid before ALATCH fall	38	83		ns
$t_{su}(LA-JL)$ Setup time, low address valid before ALATCH fall	38	83		ns
$t_d(JL-LA)$ Delay time, low address hold after ALATCH fall	131	166		ns
$t_d(RW-JL)$ Delay time, R/W valid before ALATCH fall	43	83		ns
$t_h(EH-RW)$ Hold time, R/W valid after ENABLE rise	106	166		ns
$t_h(EH-HA)$ Hold time, high address valid after ENABLE rise	106	166		ns
$t_{su}(Q-EH)$ Setup time, data out valid before ENABLE rise	96	166		ns
$t_h(EH-Q)$ Hold time, data out valid after ENABLE rise	106	166		ns
$t_d(LA-EL)$ Delay time, low address high-Z to ENABLE fall	38	83		ns
$t_d(EH-A)$ Delay time, ENABLE rise to next address drive	106	166		ns
$t_d(EL-D)$ Delay time, data in after ENABLE fall	90	250		ns
$t_a(A-D)$ Access time, data in from valid address	300	400		ns
$t_d(A-EH)$ Delay time, ENABLE high after address valid	450	500		ns
$t_h(EH-D)$ Hold time, data input valid after ENABLE rise	0			ns
$t_d(EH-JH)$ Delay time, ENABLE rise to ALATCH rise	106	166		ns
$t_d(CH-EL)$ Delay time, CLKOUT rise to ENABLE fall		30		ns

† $V_{CC} = 5 \text{ V} \pm 10\%$, $t_c(C) = 2/\text{freq}$

CLKIN duty cycle = 50%

 $f_{osc} = 0.5 \text{ to } 6.0 \text{ MHz}$

Figure 4-28. Read and Write Cycle Timing for the TMS70C02, TMS70C42, and TMS70C82



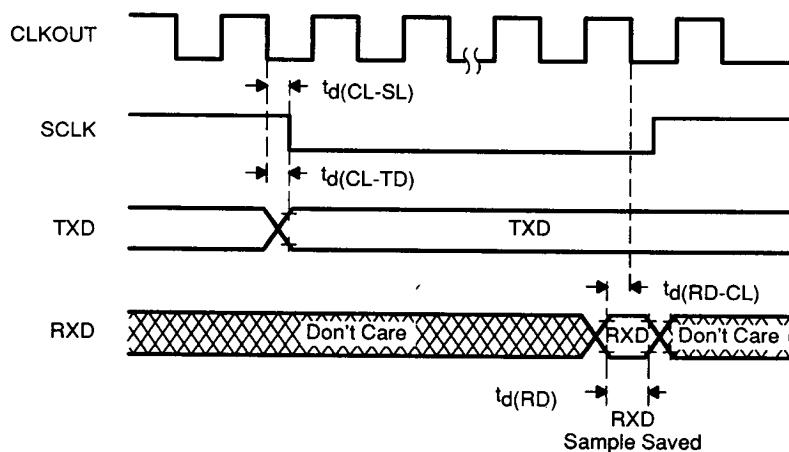
4.5.1 Serial Port Timing

4.5.1.1 Internal Serial Clock

Table 4-35. Timing Parameters for Internal Serial Clock for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Typ	Unit
$t_{d(CL-SL)}$ CLKOUT low to SCLK low	$1/4 t_c(C)$	ns
$t_{d(CL-TD)}$ CLKOUT low to new TXD data	$1/4 t_c(C)$	ns
$t_{d(RD-CL)}$ RXD data valid before CLKOUT low	$1/4 t_c(C)$	ns
$t_{d(RD)}$ RXD data valid time	$1/2 t_c(C)$	ns

Figure 4-29. Timing Diagram for Internal Serial Clock for the TMS70C02, TMS70C42, and TMS70C82



Notes:

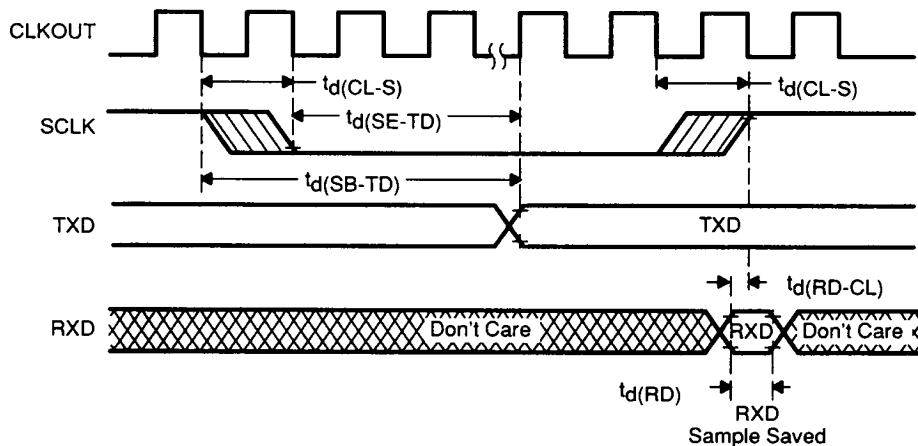
- 1) The CLKOUT signal is not available in single-chip mode.
- 2) $CLKOUT = t_c(C)$.

4.5.1.2 External Serial Clock

Table 4-36. Timing Parameters for External Serial Clock for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Typ	Unit
$t_d(RD-CL)$ RXD data valid before CLKOUT low	$1/4 t_c(C)$	ns
$t_d(RD)$ RXD data valid time	$1/2 t_c(C)$	ns
$t_d(SB-TD)$ Start of SCLK sample to new TXD data	$3 1/4 t_c(C)$	ns
$t_d(SE-TD)$ End of SCLK sample to new TXD data	$2 1/4 t_c(C)$	ns
$t_d(CL-S)$ Clockout low to SCLK transition	$t_c(C)$	ns

Figure 4-30. Timing Diagram for External Serial Clock for the TMS70C02, TMS70C42, and TMS70C82



- Notes:**
- 1) The CLKOUT signal is not available in single-chip mode.
 - 2) $CLKOUT = t_c(C)$.
 - 3) SCLK sampled; if SCLK = 1 then 0, fall transition found.
 - 4) SCLK sampled; if SCLK = 0 then 1, rise transition found.